

OUR MISSION IS THAT YOU ACHIEVE YOURS



SPACE CAMERAS

SPACE CAMERAS FOR VIDEOS AND IMAGING

Overview

3D PLUS Space Camera family offers standard products targeting a wide range of imaging applications and are designed for space environment. Using high reliability and qualified parts, and with widely used communication interfaces, IRIS Space Camera Family is an efficient and competitive choice for your space missions.



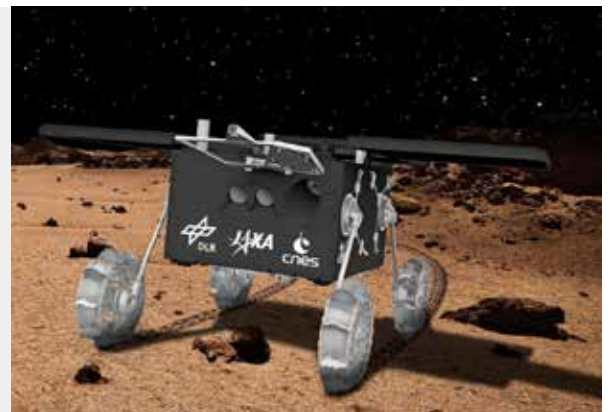
Credit: NASA

PLATFORM AND PAYLOAD MONITORING

3D PLUS Space Cameras are perfectly suitable for monitoring applications, allowing to verify the correct deployment of your spacecraft's solar panels and antennas, or to watch over the operation of the instruments (drill monitor, robotic arm,...). They also allow to widely communicate on the mission's operations.

GUIDANCE, NAVIGATION AND CONTROL

3D PLUS Space Cameras are efficient solutions for GN&C applications, and are used as rover navigation cameras and in-orbit servicing main imaging sensors. Their modularity allows to select the most suitable configuration for your application.



Credit: JAXA/CNES/DLR



DETECTION, OBSERVATION AND TRACKING

3D PLUS Space Cameras expanding family provides efficient and simple solutions for observation applications, such as earth observation, debris detection and tracking, or spacecraft situational awareness (SSA).

STANDARD SPACE CAMERAS LINE-UP

3D PLUS offers multiple off-the-shelf Space Camera configurations with its IRIS and IRIS HD line-up, based on its CASPEX 4M and CASPEX 12M Camera Heads and existing space qualified optics.

	IRIS 8mm	IRIS 11mm	IRIS 25mm	IRIS 50mm	IRIS HD 8mm
Focal Length	7.9mm	11.6mm	25mm	50mm	7.9mm
FoV (Edge to Edge)	80° (H) x 80° (V)	56° (H) x 56° (V)	25° (H) x 25° (V)	12.5° (H) x 12.5° (V)	82° (H) x 74° (V)
Aperture	f/8	f/9	f/9	f/7.5	f/8
Optical angular resolution	<1.2 mrad	1.3 mrad	0.25 mrad	0.125 mrad	<1.2 mrad
Spectral bandwidth	450-700nm	450-700nm	450-700nm	450-700nm	450-700nm
Camera Core	CASPEX 4M	CASPEX 4M	CASPEX 4M	CASPEX 4M	CASPEX 12M
Sensor Resolution	4 Mpixels Global shutter 2048 x 2048	4MPixels Global shutter 2048 x 2048	4 Mpixels Global shutter 2048 x 2048	4MPixels Global shutter 2048 x 2048	12MPixels Global shutter 4096 x 3000
Integrated processing	Binning, windowing mode	Binning, windowing mode	Binning, windowing mode	Binning, windowing mode	Binning, Windowing, H264 compression
Performances	2 full frames per second	2 full frames per second	2 full frames per second	2 full frames per second	30 frames per second in Full HD
Interface	Space Wire	Space Wire	Space Wire	Space Wire	Space Wire
Mass	< 400g	< 400g	< 400g	< 400g	< 800g
Volume	86x72x69 mm ³	86x72x76 mm ³	86x72x80 mm ³	86x72x120 mm ³	90x84x92 mm ³
Power supply	4.5 to 9V	4.5 to 9V	4.5 to 9V	4.5 to 9V	4.5 to 5.5V
Average Power Consumption (25°C)	1.5W	1.5W	1.5W	1.5W	5W
Operationnnal Temperature	-40 to +55°C	-40 to +55°C	-40 to +55°C	-40 to +55°C	-55 to +55°C
Environment	LEO, GEO and Deep Space missions	LEO, GEO and Deep Space missions	LEO, GEO and Deep Space missions	LEO, GEO and Deep Space missions	LEO, GEO and Deep Space missions



SPACE CAMERAS RELATED PRODUCTS

CASPEX Camera Heads

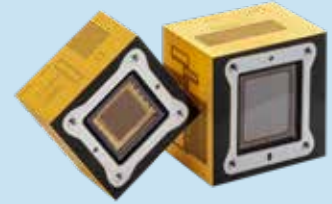
3D PLUS successful CASPEX camera heads product line offers multiple off-the-shelf solutions for your optical instruments. For specific applications not covered by our cameras, these camera heads bring the performances and miniaturization needed for highly constrained missions.

APPLICATIONS

Earth observation, Planetology
Platform monitoring (equipment, payload)
GN&C (Rendez-vous, navigation, tracking)
Spectroscopy

FEATURES

Highly miniaturized All-in-one module
Generic reconfigurable FPGA based architecture
Radhard by design



	CASPEX 4M Visible	CASPEX 12M Visible	CASPEX SWIR
RESOLUTION	2048 x 2048 pixels, 5.5µm pitch, RGB or Mono	4096x3000 pixels, 3.45µm pitch, RGB or Mono	1280x1024 pixels, 5µm pitch
OPTOELECTRONIC PERFORMANCES	Read Noise : 13e- Dark Current : 125e-/s FWC: 13.5ke-	Read Noise : 2.5e- Dark Current : 10e-/s FWC: 11ke-	Read Noise : 240e- Dark Current : 28ke-/s FWC: 170ke-
SPECTRAL RESPONSE	400-1000 nm	400-1000 nm	400-1700nm
INTERFACES	12 LVDS pairs, 13 GPIO 4.5 to 9V power supply, average consumption 1.5W at 25°C	12 LVDS pairs, 13 GPIO 4.5 to 9V power supply, average consumption 5W at 25°C	22 configurable LVDS pairs 4.5 to 5.5 power supply, average consumption 5W at 25°C
OPERATING TEMPERATURE RANGE	-40°C to +70°C	-55°C to +70°C	-55°C to +70°C
RELIABILITY	TID > 30 krad(Si) SEL immune	TID > 40 krad(Si) SEL immune	TID > 40 krad(Si) SEL immune
DIMENSIONS	35x35x23 mm ³ , 62g	40x40x45mm ³ , 125g	40x40x50mm ³ , 140g

FPGA Code and IPs

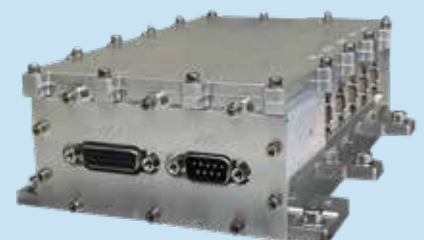
3D PLUS offers multiple IP products for its FPGA-based camera architecture. From full turn-key solutions with standard interface (ex: SpaceWire, CameraLink,...), Controller IP Cores, to fully custom FPGA designs, 3D PLUS Camera solutions can answer all your image processing needs.

Evaluation Kit and GSE

3D PLUS offers ready-to-use prototyping solutions and ground support equipments for each of its Space Camera products. From electrical interface to acquisition software, the 3DEV evaluation kits allows you to easily characterize and integrate our camera solutions on your platform.

Electronic Control Unit

3D PLUS developed an electronic control unit, integrating a 28V-5V DC-DC converter, communication interface protection, and Multi cameras router, able to operate up to seven IRIS Cameras, with a redundant spacewire connection to the platform, to provide a multi-camera monitoring system for spacecrafts.



Flight **HERITAGE**



SuperCam Perseverance Rover

3D PLUS CASPEX 4M camera head is part of Perseverance's SuperCam instrument, providing imaging capability for soil monitoring and long distance imaging, as the opto-electronic head of the Remote Micromager sub-equipment. It landed on Mars in early 2021.



Credit: NASA/JPL-Caltech/LANL/CNES/CNRS



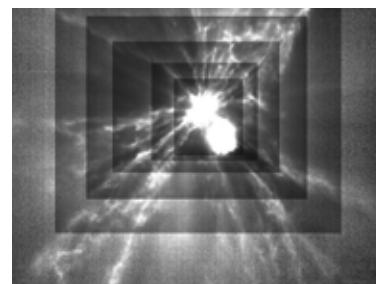
EyeSat

3D PLUS CASPEX 4M camera head is the optoelectronic core of the Iris instrument, on EyeSat 3U nanosatellite. It was launched in 2019 in LEO and used for solar system study and zodiacal light analysis.



Dart LICIAcube

3D PLUS CASPEX 4M camera head is the optoelectronic head of the LEIA camera, that was used in 2022 to confirm the DART spacecraft impact with the Dimorphos asteroid.



Credit: ASI/NASA/APL



Mars Sample Return

3D PLUS IRIS and IRIS HD Space cameras are part of the ongoing MSR program, providing imaging capability for both the Earth Return Orbiter (Multicamera monitoring system, especially martian sample capture monitoring) and Sample Return Lander robotic arm (Sample Transfer Arm, as critical sample detection and capture camera).



Credit: ESA/NASA



AN INNOVATIVE COMPANY

COMPANY OVERVIEW

3D PLUS is a world leading supplier of advanced high density 3D microelectronic products and Die/Wafer Level stacking technology meeting the demand for high reliability, high performance and very small size of today's and tomorrow's electronics.

We offer standard products and custom System-in-Package (SiP) solutions based on our patented technology. The company is ISO 9001 : 2015 certified and its stacking technologies is qualified by the European Space Agency for Space applications.



SPACE EXPERTISE

Recognized for their electrical performances, miniaturization, quality, reliability and radiation assurance level, 3D PLUS's Space qualified products bring key advantages to all Space application fields:

- **Consumer Applications:** telecommunication, navigation, internet...
- **Durable Development:** environment and climate monitoring
- **Defense & Security:** Earth observation
- **Space Transportation:** launch and manned space vehicles
- **Science:** astronomy, space exploration and interplanetary missions

FLIGHT PROVEN PRODUCTS

With more than 200.000 modules in orbit today and a failure-free flight heritage of more than 25 years, 3D PLUS is the largest Space Qualified MCM manufacturer in Europe.

3D PLUS's products are used by all the major space agencies and customers worldwide. They are used in numerous missions: Dart LiciaCube, Mars 2020, Curiosity, New Horizons, Parker Solar Probe, Proba-1, ISS, Rosetta, Sentinel, Bepi-Colombo, Insight, OneWeb, Solar Orbiter and many more in the near future.

3D PLUS BENEFITS

- HIGH DENSITY
- HIGH SPEED PERFORMANCE
- SMALL FORM FACTOR
75 % space and weight savings in the design
- HIGH RELIABILITY
- SPACE QUALIFIED TECHNOLOGY
- FLIGHT PROVEN PRODUCTS
- RADIATION HARDENED (TID, SEE)
- LONG TERM SUPPLY GUARANTY

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